

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
20V	12mΩ@4.5V	12A
	18mΩ@2.5V	

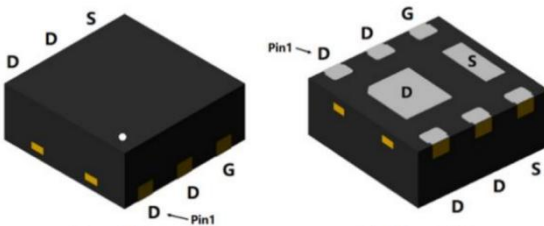
### Feature

- High power and current handing capability
- Ultra low on-resistance with low gate charge

### Application

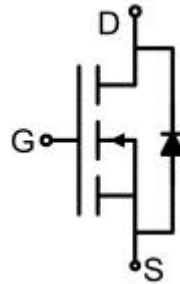
- Motor/Body Load Control
- Load Switch Load Switch
- DC-DC converters
- Relay driver

### Package

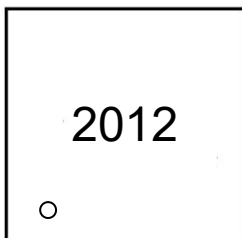


DFN2\*2-6L

### Circuit diagram



### Marking



### Absolute maximum ratings ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current	$I_D$	12	A
Pulsed Drain Current <sup>1)</sup>	$I_{DM}$	50	A
Power Dissipation	$P_D$	2	W
Thermal Resistance, Junction-to-Ambient <sup>2)</sup>	$R_{\theta JA}$	57	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

### Electrical characteristics ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	20			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$			1	$\mu\text{A}$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 12\text{V}, V_{DS} = 0\text{V}$			$\pm 10$	$\mu\text{A}$
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.45	0.7	1.0	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = 4.5\text{V}, I_D = 8\text{A}$		8.5	12	m $\Omega$
		$V_{GS} = 2.5\text{V}, I_D = 6\text{A}$		12.5	18	
<b>Dynamic characteristics<sup>3)</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 10\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		1030		pF
Output Capacitance	$C_{oss}$			185		
Reverse Transfer Capacitance	$C_{rss}$			174		
Total Gate Charge	$Q_g$	$V_{DS} = 10\text{V}, V_{GS} = 10\text{V}, I_{DS} = 6\text{A}$		28.1		nC
Gate-Source Charge	$Q_{gs}$			2.8		
Gate-Drain Charge	$Q_{gd}$			6.4		
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 10\text{V}, V_{Gen} = 10\text{V}, I_{DS} = 6\text{A}, R_G = 1.8\Omega$		12		nS
Turn-on rise time	$t_r$			32		
Turn-off delay time	$t_{d(off)}$			29		
Turn-off fall time	$t_f$			17		

Notes:

- 1) Pulse Test: Pulse Width  $\leq 100\mu\text{s}$ , Duty Cycle  $\leq 2\%$ , Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)} = 150^\circ\text{C}$
- 2) Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.
- 3) Guaranteed by design, not subject to production.

## Typical Characteristics

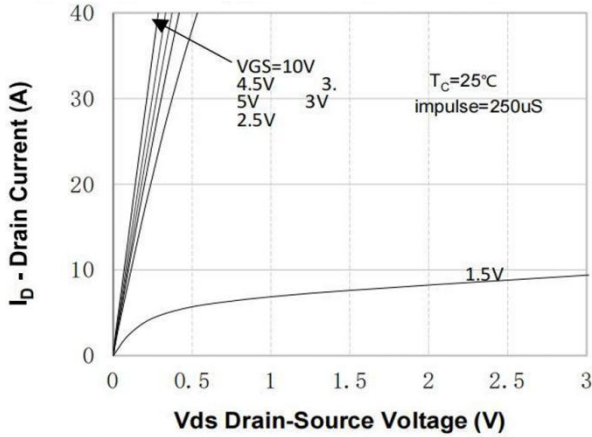


Figure 1. On-Region Characteristics

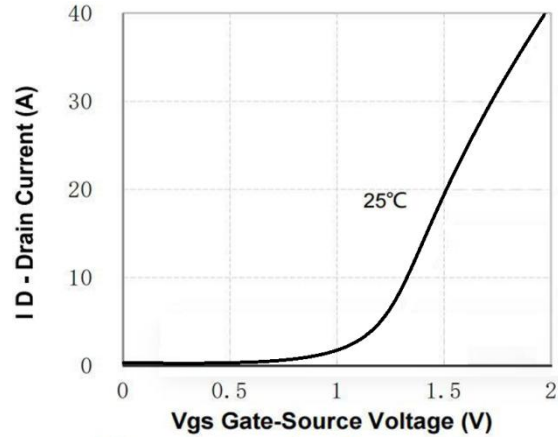


Figure 2. Transfer Characteristics

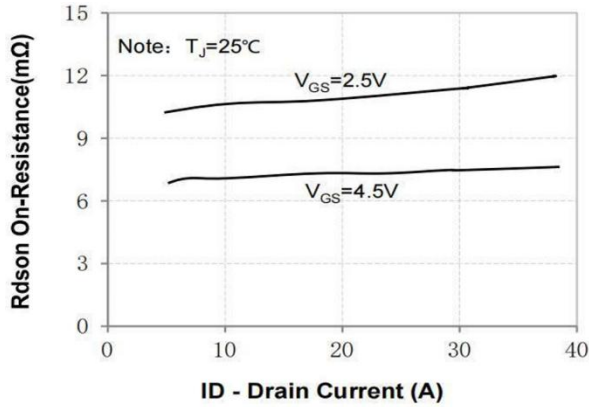


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

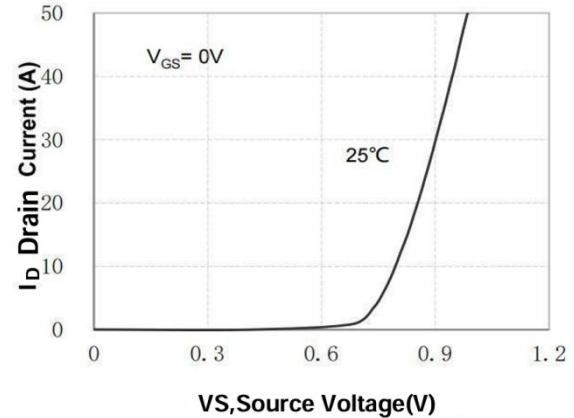


Figure 4. Body Diode Forward Voltage Variation with Source Current

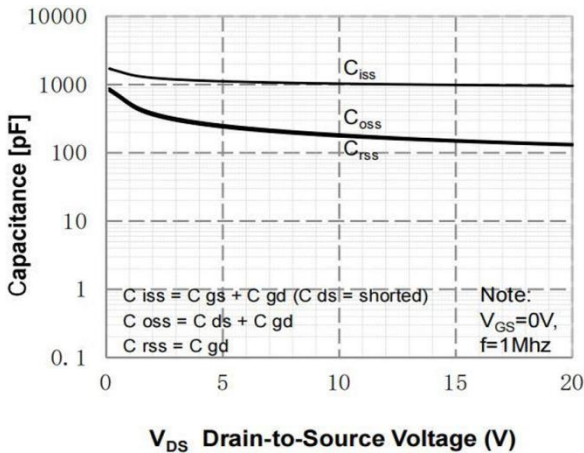


Figure 5. Capacitance Characteristics

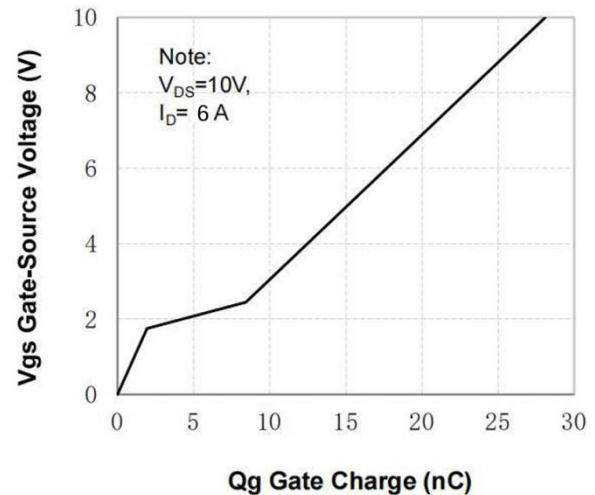
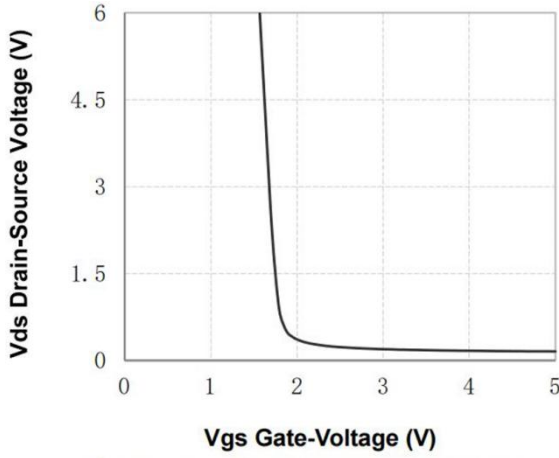
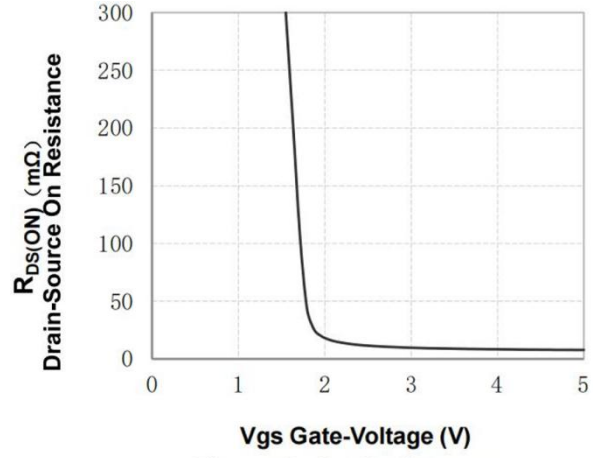


Figure 6. Gate Charge Characteristics

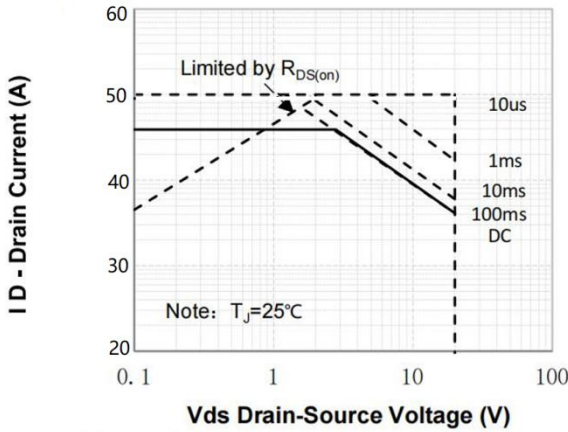
## Typical Characteristics



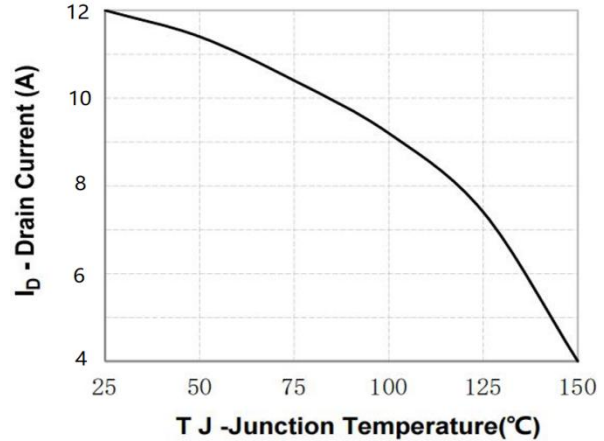
**Figure 7. Vds Drain-Source Voltage vs Gate Voltage**



**Figure 8. On-Resistance vs Gate Voltage**

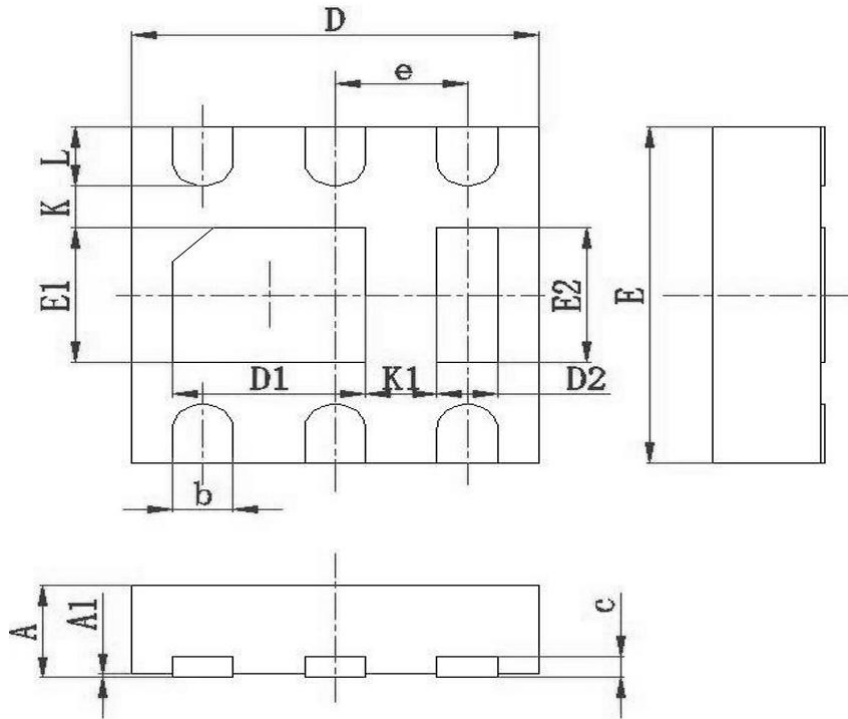


**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Continuous Drain Current vs Temperature**

### DFN2\*2-6L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.500	0.600	0.020	0.024
A1	0.000	0.050	0.000	0.002
b	0.250	0.350	0.010	0.014
c	0.127 BSC.		0.005 BSC.	
D	1.900	2.100	0.075	0.083
D1	0.900	1.000	0.035	0.039
D2	0.250	0.350	0.010	0.014
e	0.650 BSC.		0.026 BSC.	
E	1.900	2.100	0.075	0.083
E1	0.750	0.850	0.030	0.033
E2	0.750	0.850	0.030	0.033
K	0.250 BSC.		0.010 BSC.	
K1	0.350 BSC.		0.014 BSC.	
L	0.300	0.400	0.012	0.016